

ABSTRACT

A post-liner/barrier/seed deposition sputter etch is used to remove an overhang portion (111) of a physical vapor deposited (PVD) film (110, 112, 214). A PVD process typically results in a liner/barrier (110,214) or seed (112) layer having thicker overhang portion (111) at the upper corners of a trench (108), via (106), or contact (212). A post deposition sputter etch using low bias is used to reduce the thickness of the overhang portion (111) and avoid a seam in a subsequent fill process.

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